# NPN Silicon Power Transistor

# **High Voltage SWITCHMODE Series**

Designed for use in electronic ballast (light ballast) and in SWITCHMODE Power supplies up to 50 W.

### **Features**

- Improved Efficiency Due to:
  - ◆ Low Base Drive Requirements (High and Flat DC Current Gain h<sub>FE</sub>)
  - ♦ Low Power Losses (On-State and Switching Operations)
  - Fast Switching:  $t_{fi} = 100 \text{ ns (typ)}$  and  $t_{si} = 3.2 \mu \text{s (typ)}$
  - @  $I_C = 2.0 \text{ A}$ ,  $I_{B1} = I_{B2} = 0.4 \text{ A}$
- Full Characterization at 125°C
- Tight Parametric Distributions Consistent Lot-to-Lot
- These Devices are Pb-Free and are RoHS Compliant\*

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Sustaining Voltage	V <sub>CEO</sub>	400	Vdc
Collector-Base Breakdown Voltage	V <sub>CES</sub>	700	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	9.0	Vdc
Collector Current - Continuous - Peak (Note 1)	I <sub>C</sub>	5.0 10	Adc
Base Current	Ι <sub>Β</sub>	2.0	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	75 0.6	W W/°C
Operating and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to 150	°C

## THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.65	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

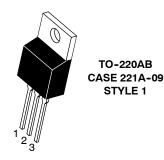
1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.



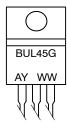
# ON Semiconductor®

http://onsemi.com

# POWER TRANSISTOR 5.0 AMPERES, 700 VOLTS, 35 AND 75 WATTS



### MARKING DIAGRAM



BUL45 = Device Code A = Assembly Location

Y = Year

WW = Work Week
G = Pb-Free Package

### **ORDERING INFORMATION**

Device	Package	Shipping
BUL45G	TO-220 (Pb-Free)	50 Units / Rail

1

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic				Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS								
Collector-Emitter Sustaining Voltage (I <sub>C</sub> = 100 mA, L = 25 mH)				V <sub>CEO(sus)</sub>	400	-	-	Vdc
Collector Cutoff Current (V <sub>CE</sub> = Rated V <sub>CEO</sub> , I <sub>B</sub> = 0)			I <sub>CEO</sub>	-	-	100	μAdc	
Collector Cutoff Current (V <sub>CE</sub> =	I <sub>CES</sub>	-	-	10 100	μAdc			
Emitter Cutoff Current (V <sub>EB</sub> = 9.	.0 Vdc, I <sub>C</sub> = 0)			I <sub>EBO</sub>	-	-	100	μAdc
ON CHARACTERISTICS								
Base-Emitter Saturation Voltag				V <sub>BE(sat)</sub>				Vdc
$(I_C = 1.0 \text{ Adc}, I_B = 0.2 \text{ Adc})$ $(I_C = 2.0 \text{ Adc}, I_B = 0.4 \text{ Adc})$				, ,	-	0.84 0.89	1.2 1.25	
Collector-Emitter Saturation Vo		I <sub>B</sub> = 0.2 A T <sub>C</sub> = 125		V <sub>CE(sat)</sub>	-	0.175 0.150	0.25 -	Vdc
Collector-Emitter Saturation Vo		I <sub>B</sub> = 0.4 A T <sub>C</sub> = 125		V <sub>CE(sat)</sub>	-	0.25 0.275	0.4	Vdc
DC Current Gain (I <sub>C</sub> = 0.3 Adc,	V <sub>CE</sub> = 5.0 Vdc)	T 405		h <sub>FE</sub>	14	-	34	-
(I <sub>C</sub> = 2.0 Adc, V <sub>CE</sub> = 1.0 V		$T_{\rm C} = 125$	(°C)		7.0	32 14	-	
	· (	$T_{\rm C} = 125$	°C)		5.0	12	-	
(I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 5.0 \					10	22	-	
DYNAMIC CHARACTERISTICS		a f 10	MILL			10	1	MILE
Current Gain Bandwidth (I <sub>C</sub> = 0			IVITZ)	f <sub>T</sub>	-	12	75	MHz
Output Capacitance (V <sub>CB</sub> = 10 )		/IHZ)		C <sub>ob</sub>	-	50	75	pF
Input Capacitance (V <sub>EB</sub> = 8.0 V	ac) I		I	C <sub>ib</sub>	-	920	1200	pF
	(I <sub>C</sub> = 1.0 Adc I <sub>B1</sub> = 100 mAdc V <sub>CC</sub> = 300 V)	1.0 μs	(T <sub>C</sub> = 125°C)	V <sub>CE</sub> (Dyn sat)	-	1.75 4.4	-	· Vdc
Dynamic Saturation Voltage: Determined 1.0 μs and 3.0 μs		3.0 μs	(T <sub>C</sub> = 125°C)		-	0.5 1.0	-	
respectively after rising I <sub>B1</sub> reaches 90% of final I <sub>B1</sub>	(I <sub>C</sub> = 2.0 Adc I <sub>B1</sub> = 400 mAdc V <sub>CC</sub> = 300 V)	1.0 μs	(T <sub>C</sub> = 125°C)		-	1.85 6.0	-	
(see Figure 18)		3.0 μs	(T <sub>C</sub> = 125°C)		-	0.5 1.0	-	
SWITCHING CHARACTERIST	ICS: Resistive Load	ŀ						
Turn-On Time	(I <sub>C</sub> = 2.0 Adc, I <sub>B1</sub> = Pulse Width = 20 µ		4 Adc (T <sub>C</sub> = 125°C)	t <sub>on</sub>	-	75 120	110 -	ns
Turn-Off Time	Duty Cycle < 20% V <sub>CC</sub> = 300 V (T <sub>C</sub> = 125°C)			t <sub>off</sub>	-	2.8 3.5	3.5 -	μs
SWITCHING CHARACTERIST	ICS: Inductive Load	d (V <sub>CC</sub> =	15 Vdc, L <sub>C</sub> = 200	μH, V <sub>clamp</sub> = 30	00 Vdc)	•	•	•
Fall Time	$(I_C = 2.0 \text{ Adc}, I_{B1} = I_{B2} = 0.4 \text{ Adc})$	= 0.4 Adc	(T <sub>C</sub> = 125°C)	t <sub>fi</sub>	70 -	- 200	170 -	ns
Storage Time			(T <sub>C</sub> = 125°C)	t <sub>si</sub>	2.6	- 4.2	3.8	μs
Crossover Time			(T <sub>C</sub> = 125°C)	t <sub>c</sub>	-	230 400	350 -	ns
Fall Time	(I <sub>C</sub> = 1.0 Adc, I <sub>B1</sub> = 100 mAdc I <sub>B2</sub> = 0.5 Adc) (T <sub>C</sub> = 125°C)			t <sub>fi</sub>	-	110 100	150 -	ns
Storage Time	(T <sub>C</sub> = 125°C)			t <sub>si</sub>	-	1.1 1.5	1.7	μs
Crossover Time	(T <sub>C</sub> = 125°C)			t <sub>c</sub>	-	170 170	250 -	ns
Fall Time	$(I_C = 2.0 \text{ Adc}, I_{B1} = 250 \text{ mAdc} \ I_{B2} = 2.0 \text{ Adc})$ $(T_C = 125^{\circ}C)$			t <sub>fi</sub>	-	80	120	ns
Storage Time	(T <sub>C</sub> = 125°C)			t <sub>si</sub>	-	0.6	0.9	μs
Crossover Time	(T <sub>C</sub> = 125°C)			t <sub>c</sub>	-	175	300	ns

## TYPICAL STATIC CHARACTERISTICS

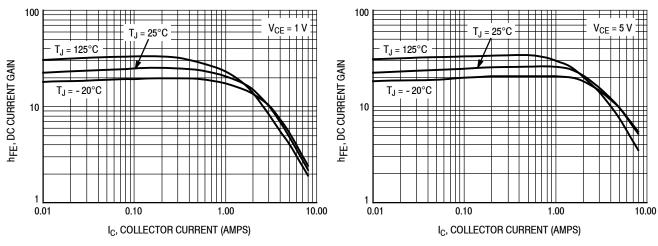


Figure 1. DC Current Gain @ 1 Volt

Figure 2. DC Current Gain at @ 5 Volts

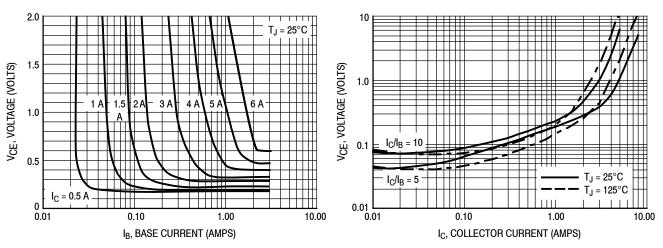


Figure 3. Collector-Emitter Saturation Region

Figure 4. Collector-Emitter Saturation Voltage

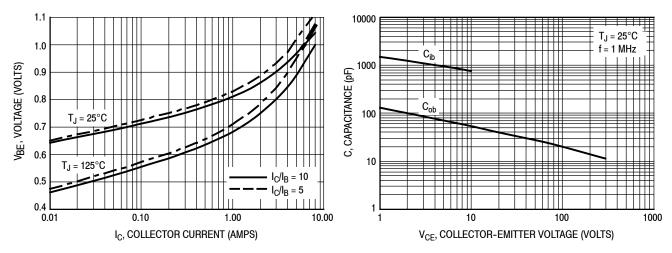
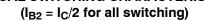
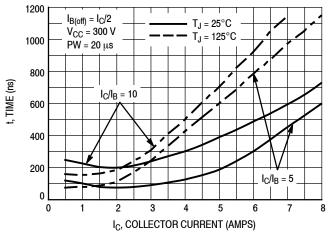


Figure 5. Base-Emitter Saturation Region

Figure 6. Capacitance

# TYPICAL SWITCHING CHARACTERISTICS

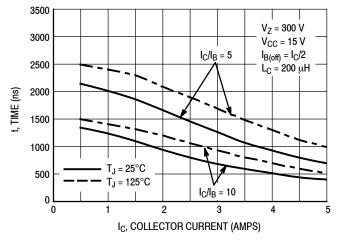




3000  $I_{B(off)} = I_{C}/2$  $T_J = 25^{\circ}C$ V<sub>CC</sub> = 300 V  $I_C/I_B = 5$ T<sub>J</sub> = 125°C 2500  $PW = 20 \; \mu\text{s}$ 2000 t, TIME (ns)  $I_C/I_B = 10$ 1500 1000 500 IC, COLLECTOR CURRENT (AMPS)

Figure 7. Resistive Switching, ton

Figure 8. Resistive Switching, toff



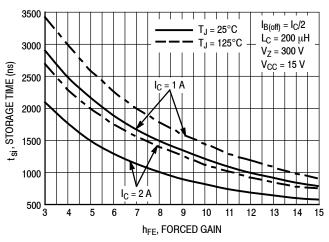
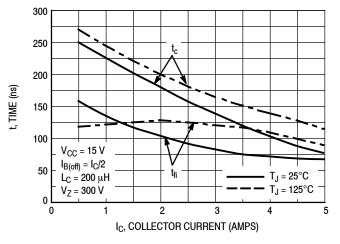


Figure 9. Inductive Storage Time, tsi

Figure 10. Inductive Storage Time, tsi(hFE)



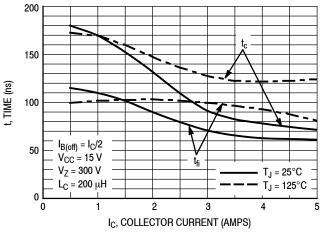


Figure 11. Inductive Switching,  $t_c$  &  $t_{fi}$ ,  $I_C/I_B = 5$ 

Figure 12. Inductive Switching,  $t_c \& t_{fi}$ ,  $I_C/I_B = 10$ 

# TYPICAL SWITCHING CHARACTERISTICS $(I_{B2} = I_C/2 \text{ for all switching})$

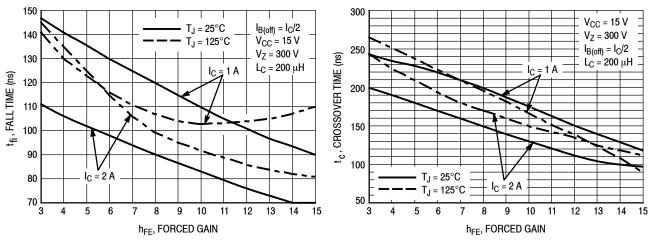


Figure 13. Inductive Fall Time, tfi(hFE)

Figure 14. Crossover Time

## **GUARANTEED SAFE OPERATING AREA INFORMATION**

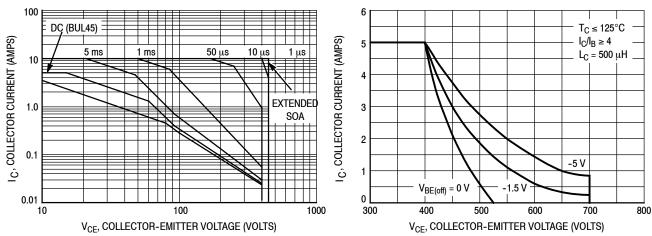


Figure 15. Forward Bias Safe Operating Area

POWER DERATING FACTOR

0.2

20

40

60

Safe operating area curves indicate  $I_C$  –  $V_{CE}$  limit that must be observed for reliable operation; i. must not be subjected to greater dissipation indicate. The data of Figure 15 is based on  $T_C$  variable depending on power level. Second belimits are valid for duty cycles to 10% but must  $T_C \ge 25^{\circ}C$ . Second breakdown limitations do not as thermal limitations. Allowable current at the valid for duty cycles to 10% but must  $T_C \ge 25^{\circ}C$ . Second breakdown limitations do not as thermal limitations. Allowable current at the valid for duty cycles to 10% but must  $T_C \ge 25^{\circ}C$ . Second breakdown limitations do not as thermal limitations. Allowable current at the valid for duty cycles to 10% but must  $T_C \ge 25^{\circ}C$ . Second breakdown limitations do not as thermal limitations.

T<sub>C</sub>, CASE TEMPERATURE (°C)

Figure 17. Forward Bias Power Derating

100

120

140

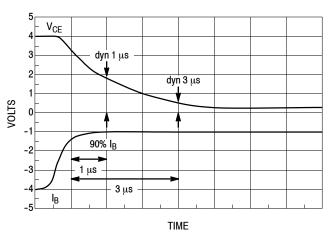
160

THERMAL DERATING

80

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I<sub>C</sub> - V<sub>CE</sub> limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate. The data of Figure 15 is based on  $T_C = 25^{\circ}C$ ;  $T_{J(pk)}$  is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when  $T_C \ge 25$ °C. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown in Figure 15 may be found at any case temperature by using the appropriate curve on Figure 17. T<sub>J(pk)</sub> may be calculated from the data in Figures 20. At any case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown. For inductive loads, high voltage and current must be sustained simultaneously during turn-off with the base-to-emitter junction reverse-biased. The safe level is specified as a reverse-biased safe operating area (Figure 16). This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode.

Figure 16. Reverse Bias Switching Safe Operating Area



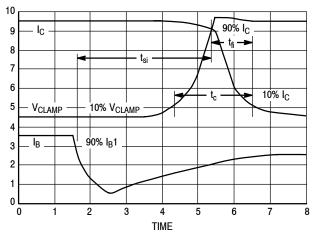
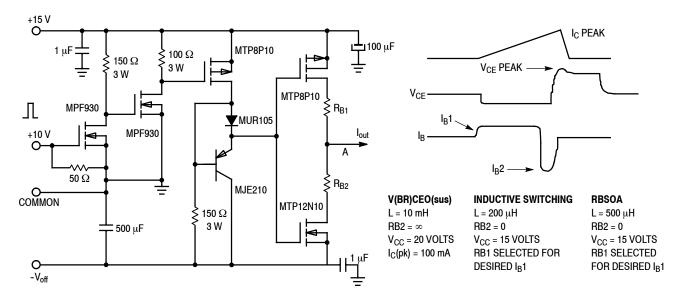


Figure 18. Dynamic Saturation Voltage Measurements

Figure 19. Inductive Switching Measurements



**Table 1. Inductive Load Switching Drive Circuit** 

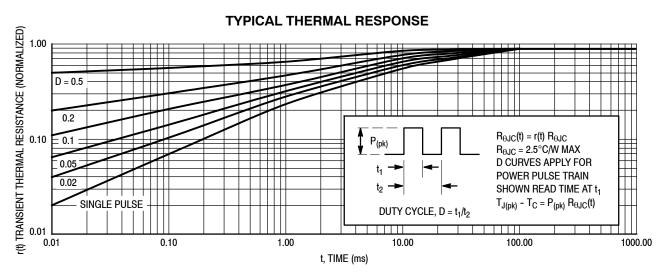


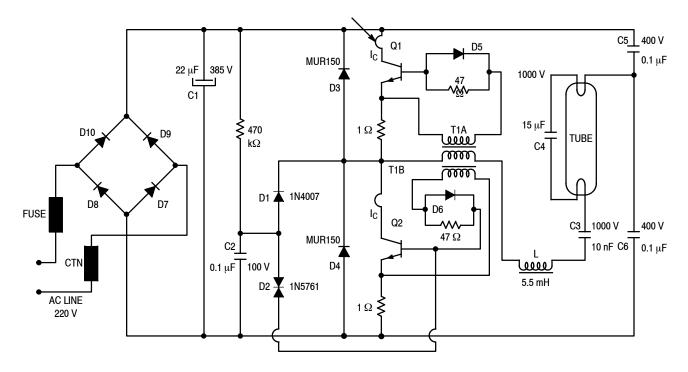
Figure 20. Typical Thermal Response ( $Z_{\theta JC}(t)$ ) for BUL45

The BUL45 Bipolar Power Transistors were specially designed for use in electronic lamp ballasts. A circuit designed by ON Semiconductor applications was built to

Secondaries: T1A: 4 turns

T1B: 4 turns

demonstrate how well these devices operate. The circuit and detailed component list are provided below.



## **Components Lists**

Q1 =	Q2 = BUL45 Transistor	All resistors are 1/4 Watt, ±5%
D1 =	1N4007 Rectifier	$R1 = 470 \text{ k}\Omega$
D2 =	1N5761 Rectifier	$R2 = R3 = 47 \Omega$
D3 =	D4 = MUR150	R4 = R5 = 1 $\Omega$ (these resistors are optional, and
D5 =	D6 = MUR105	might be replaced by a short circuit)
D7 =	D8 = D9 = D10 = 1N400	C1 = 22 μF/385 V
CTN =	47 Ω @ 25°C	$C2 = 0.1 \mu\text{F}$
L =	RM10 core, A1 = 400, B51 (LCC) 75 turns,	C3 = 10  nF/1000  V
	wire $\emptyset$ = 0.6 mm	C4 = 15  nF/1000  V
T1 =	FT10 toroid, T4A (LCC)	$C5 = C6 = 0.1 \mu F/400 V$
	Primary: 4 turns	

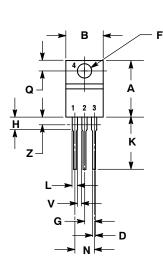
### NOTES:

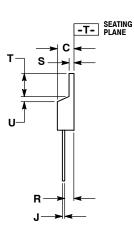
- 1. Since this design does not include the line input filter, it cannot be used "as-is" in a practical industrial circuit.
- 2. The windings are given for a 55 Watt load. For proper operation they must be re-calculated with any other loads.

Figure 21. Application Example

### PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AG** 





#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.036	0.64	0.91
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

#### STYLE 1:

- BASE
  - COLLECTOR 2.
  - EMITTER 3.
  - COLLECTOR

ON Semiconductor and IIII are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## **PUBLICATION ORDERING INFORMATION**

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative